Heavy Copper Wire Bonding
Ready for
Industrial Mass Production

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Heavy Copper Wire Bonding
Agenda

- Introduction
- Copper Wire Bonding: Advantages and Challenges
- Tool Wear and Lifetime
  - Wear mechanisms
  - Parameters influencing tool wear and lifetime
  - Impact of bonding parameters on tool wear
  - Impact of tool wear on bond quality
- Monitoring Tool Wear via Machine Data
- Cutter and Wire Guide Lifetime
- Summary and Outlook
Industry needs a next generation interconnection system for a desired rise of junction temperature and to increase lifetime.

- Aluminum does not fulfill these new power requirements.
- Heavy Cu wire is one such system available today.
- Al heavy wire bonding is state-of-the-art in connecting power devices.
- Power cycling is limited by max. operation temperature of Al wire above $0.4 \times T_{\text{melt}}$ (100°C) due to creep.
- Al wire is the weakest link - cracks run through the wire and not along the interface to the chips.
- Thermo-mechanical mismatch (Si: 2.6 ppm/K, Al: 23 ppm/K, Cu: 17 ppm/K)
- The wire material limits the lifetime. Alternative materials need to meet the requirements to increase junction temperature and lifetime.
Introduction

Copper Wire Bonding: Advantages and Challenges

Tool Wear and Lifetime
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  - Impact of bonding parameters on tool wear
  - Impact of tool wear on bond quality

Monitoring Tool Wear via Machine Data

Cutter and Wire Guide Lifetime

Summary and Outlook
Advantages and Challenges

- Currently heavy aluminum wire is widely used with limited lifetime and adequate electrical conductivity.
- Elevated junction temperature and increased lifetime in system environment is desired.
- New die attach techniques and copper wire bonding enable approximately
  - 10x higher lifetime or
  - 10x increased output power

Piotr Luniewski, Karsten Guth, Dirk Siepe,
Cu Bonds and Chip-to Substrate Joints Beyond Silver Sintering,
BPS 2010

Siepe et al., The Future of Wire Bonding is? Wire Bonding!, CIPS 2010

20 mil copper wire bonding in power modul, Infineon Technologies
Advantages and Challenges

- Technology migration to copper wire:
  - Better thermal and electrical conductivity
  - Higher homologous temperature
  - Larger current density
  - Smaller chips
  - Better long-term stability
  - Higher mechanical stability

- 2-3 times higher bonding force and ultrasonic power necessary
- Cu plated dies necessary for heavy Cu wire bonding.
- Lower lifetime of consumables compared to aluminum bonding, increased change intervals and higher costs.

<table>
<thead>
<tr>
<th></th>
<th>Aluminum</th>
<th>Copper</th>
</tr>
</thead>
<tbody>
<tr>
<td>Specific Resistance</td>
<td>0,027 Ω mm²</td>
<td>0,017 Ω mm²</td>
</tr>
<tr>
<td>Thermal conductivity</td>
<td>220 W/m K</td>
<td>400 W/m K</td>
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<tr>
<td>Thermal Expansion Coef.</td>
<td>23 ppm</td>
<td>16,5 ppm</td>
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<tr>
<td>Yield strength</td>
<td>29 MPa</td>
<td>140 MPa</td>
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<tr>
<td>Tensile strength</td>
<td>40-50 MPa</td>
<td>210-230 MPa</td>
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<tr>
<td>Elastic modulus</td>
<td>70 GPa</td>
<td>110-140 GPa</td>
</tr>
<tr>
<td>Melting temperature</td>
<td>660 °C</td>
<td>1083 °C</td>
</tr>
<tr>
<td>Typical Bondforce</td>
<td>7 N</td>
<td>25 N</td>
</tr>
<tr>
<td>Ultrasonic Power</td>
<td>100 %</td>
<td>200-300 %</td>
</tr>
</tbody>
</table>
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Wear Mechanisms

- With Al wire, material collects on the tool which then needs to be cleaned after about 100k bonds. Tool can be cleaned & reused up to 10 times.
- With heavy Cu wire bonding, strong wear is visible quite quickly.
- No build-up of Cu in the V-groove area. No cleaning possible.
- Tool can only be used once for Cu and is then discarded.

Reference tungsten carbide tool, reference parameters, 500 micron Cu wire
Wear Mechanisms – Visual appearance

- Noticeable degradation of the bond shape after just 25k bonds.
- Shiny surfaces indicate micro-slip.
Wear Mechanisms – Causes

- Wear mechanisms:
  - Abrasion
  - Plastic deformation
  - Breaking of surface material
  - Recurrent deposition of small particles of copper oxide

Initial bond

After 25k bonds

Wedge groove after 25k bonds
Tool Wear & Lifetime – Experimental Setup

- **Heraeus PowerCu Copper Wire**
  - 500 microns (20 mils)
  - Breaking load 3100 – 4800 gf
  - Elongation > 15%
  - 100 meters per spool (up to 500 m)

- **BJ939 Hesse Heavy Wire Bonder**
  - Copper/heavy ribbon bond head, back-cut, 60 kHz, bonding force up to 4200 gf, ultrasonic power up to 120 Watts
  - Note: typical bond head used for heavy Al wire is 60 kHz, 80 Watts up to 1500 gf

Source: [http://heraeus-contactmaterials.com](http://heraeus-contactmaterials.com)
Pure Cu plates 0.8 mm thick, C194
Only single bonds without loops
Reference bond tool with reference bond parameters
Made 100,000 bonds and monitored:
  - Bond shape by microscopy
  - Shear values
  - Machine process data
DOE was done to obtain the wear-optimized parameters
Tried alternative bond tool materials and bond tool tip designs
Different parameters influence tool wear and lifetime:

- **Material**
  - Tungsten carbide
  - Cermet (tip)
  - Other materials – no improvement

- **Geometry**
  - V-Groove
  - Cross groove
  - Other type to improve grip

- **Bonding parameters**

- **Looping** – not tested here
Definition of Bond Quality – 3 Criteria

- **Bond strength**
  - Measured via bond shear test
  - Shear values and shear code as a measure

- **Visual criteria**
  - Optical inspection of the top side of the bond foot
  - Topography of contact area, width and length, carving on the sides
  - Is the surface matte or shiny? (indication for micro-slip)
  - Does bond tool touchdown occur during bonding?

- **Machine process data**
Impact of Bonding Parameters on Tool Wear

- Tool lifetime was increased by a factor of 4 by using wear-optimized parameters.
- No decrease in bond strength between the two parameter sets.
- Look at 25k bonds photos between optimized and standard parameters.
Impact of Tool Wear on Bond Quality

- Bond foot visual does not correlate with shear remnants with heavy Cu wire.

New tool

100k bonds
Impact of Tool Wear on Bond Quality

- Bond foot visual does not correlate with shear remnants
- Shear values correlate with shear remnants
- … and can stay at a high level despite massive tool wear
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Monitoring Tool Wear via Machine Data

Cutter and Wire Guide Lifetime

Summary and Outlook
Piezoelectric Sensor

Monitoring Tool Wear via Machine Data

Digital Ultrasonic Generator

Bond Process Signals
- Mechanical Oscillations
- Friction
- US Current/Voltage
- Frequency
- Wire Deformation

From all these signals a quality index is automatically calculated.
Monitoring Tool Wear via Machine Data

- Not looking at a single bond but overall trend.
- ‘Tool wear monitor’ derived by filtering (black curve).
- Quality index for wire deformation shows high sensitivity towards tool wear.
- Proper setup and alignment of wire guide and cutter blade is critical to ensure optimum wire flow beneath the bond tool.

![Quality index wire deformation graph](image-url)
Monitoring Tool Wear via Machine Data

- Reference process:
  - Tungsten carbide tool as reference
  - Reference parameters, not optimized for tool wear
  - Physical degradation of the bond at 25k bonds.
  - Bond tool is worn.
Monitoring Tool Wear via Machine Data

- Optimized parameters:
  - Tungsten carbide tool as reference
  - Wear-Optimized parameters
  - Show equivalent bond quality
  - 4 x the lifetime of the bond tool
  - Tool touchdowns during bonding since 95k bonds → decrease in shear values
Cermet-tipped tool:
- Cermet-tipped tool, identical geometry
- Wear optimized parameters
- Shows slightly better lifetime than the tungsten carbide tool
- Bond tool is not hitting surface at 100k bonds.
- 2 of 3 quality requirements are not met - Bad quality monitor and bad visual.
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Cutter and Wire Guide Lifetime

Summary and Outlook
Cutter Lifetime

- Changed cutter material from hardened steel to cemented carbides for improved lifetime (initially only a few thousand).
- Alternative design avoids contact of cutter with edge of bond tool and that helps reduce wear.
- 1 million cuts is now achievable.
The wire guide showed reasonable lifetime from the beginning.

No changes were needed to the existing wire guide to reach up to 500,000 bonds (ideal conditions).

Abrasive wear on the plastic material is typical, no material build up like in aluminum bonding.

Frictional forces within the wire guide itself during wire feeding and looping have to be kept to a minimum.

Vertical and lateral alignment as well as a proper distance to the bonding tool are important to reduce frictional wear.
Summary

1. Reference bonding with tungsten carbide tool and reference parameters showed strong wear.
2. Tool wear and optical appearance of bond foot and tool tip do not correlate linearly with bond strength.
3. Increased micro-slip between tool and wire and tool touchdowns during bonding indicate tool’s EOL. Therefore the shear values will decrease.
4. Cermet-tipped tool showed little improvement in bond tool lifetime over the tungsten carbide.
5. Optimizing bond parameters had a major impact and increased the bond tool lifetime by a factor of 4.
6. Changing cutter blade tip from hardened steel to cemented carbide improved cutting up to 1,000,000 cuts.

7. Wire guide showed reasonable lifetime of up to 500,000 bonds without optimization.

8. Machine data allowed online monitoring of bond tool wear to trigger optimal bond tool change.

Future Outlook

- Further lifetime improvements with new bond tool materials are being considered.
- Implementation of tool wear monitor onto the bonding machine.
Thank you.